



FOR IMMEDIATE RELEASE

Buc, France, February 2009, 27th – European Space Agency (ESA) renews successfully 3D PLUS Capability Approval Certificate for Space Applications until January 2011

3D Plus is very pleased to announce the Successful Renewal of its Capability Approval Certificate for Space Applications.

Thanks to Capability Approval Certificate, 3D Plus is classified as a category 1 hybrid manufacturer - the highest quality grade defined by ESA in the ECSS Standard , ECSS-Q-60-05A, Generic procurement requirements for hybrid microcircuits intended for use in ESA and other European spacecraft and Space segment hardware.

From September 2008, several inspections, documentation reviews, and product technology analysis and tests have been carried out by European Space Agency, and the quality of our technology and products has been proved again.

“The Successful Renewal of our Capability Approval Certificate for Space Applications is the recognition of the very high reliability and quality of our products and technologies. We received the same feedbacks from our worldwide customers, and in 2009, with more than 30 000 modules in Space, and, with more than 9 years of Flight Heritage with no Failure, 3D Plus is the largest Space qualified catalogue products and custom System-In-Packages (SiPs) manufacturer in Europe.” said Pierre-Eric Berthet, 3D Plus Director of Sales and Marketing.

3D Plus products fly in numerous satellite programs for all major space agencies worldwide. Most of the Space missions launched recently, or, to be launched soon embeds 3D Plus Modules. Current customers’ portfolio includes the major Aerospace prime contractors and equipment manufacturers spread over more than 30 countries.

About 3D PLUS company:

Founded in 1995 as a spin-off of Thales, 3D Plus has become a worldwide actor for the advanced high density 3D package and die stacking technology meeting the demand for high reliability, extreme performance and very small size electronics.

Its portfolio of patented and very advanced stacking technologies starts with Package scale upward to die-size and wafer-level packaging techniques and provides leading edge, highly integrated and rugged modules embedding Active, Passive, Opto-electronics and MEMS/MOEMS components.

With a broad range of catalogue products including memory modules, camera heads, power converters and computer modules, with its very miniaturized System-In-Package solutions and by Licensing its technologies, 3D PLUS meets the requirements of high technology industries in industrial, telecom., computer/blade server, military, avionics, medical and space markets.

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